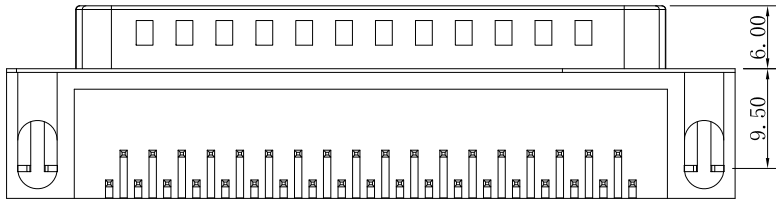
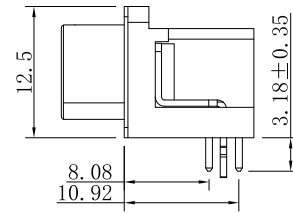
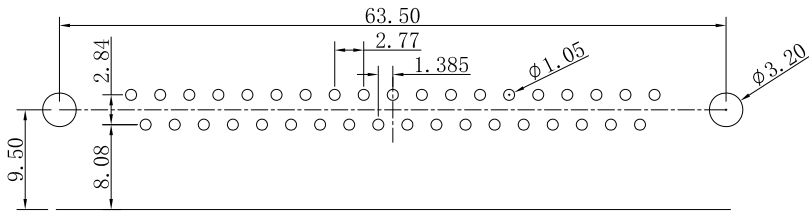


The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements



CHARACTERISTICS:

1. RATED VOLTAGE: 250V AC CD
2. RATED CURRENT: 3.0AMP
3. CONTACT RESISTANCE: 30mΩ Max.
4. INSULATION RESISTANCE: 1000 MΩ MIN. 500V DC
5. Electric Pressure: Keeping 60 second in AC 500V/1mA
6. Operating temperature: -55°C~105°C
7. INSERTION/EXTRACTION FORCE PER CONTACT: 12.5Kg Max  
1.1Kg Min.



PCB layout

Specification Type (1:2)				
A	B	C	D	E
	4.80	5.80	4.80	5.80

ORDER INFORMTION

P/N: WLDBM9-371XXX042

Number of Contact: \_\_\_\_\_

Contact Type: \_\_\_\_\_  
1: DIP

Plating Contact: \_\_\_\_\_  
1: Gold Flash  
3: Au: 3U"  
6: Au: 30U"

SCREW: \_\_\_\_\_

Housing color: \_\_\_\_\_  
A: Black  
S: Nature

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART. NO:	DWG. NO:	
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	21.03.11	WLDBM9-371XXX042	ENDE05	
			UNIT: mm	0.00±0.25	X° ±3°	DESIGNER	Ding_Bo	21.03.11	TITLE:		REV: A0      SHEET: 1/1
			SIZE: A4	0.000±0.10	X° X'±2°	DRAWN	Ou_Jian	21.03.11	DR 37M 8.08 90° DIP		